

### General Description

The SY2A23002A high-efficiency synchronous Buck converter can deliver 2A output current over an input voltage range from 2.8V to 5.5V. It uses built-in power MOSFETs to supply a resistor-configurable output voltage between 0.6V and  $V_{IN}$ . The fixed 2.35MHz switching frequency allows for small external inductor and capacitor values.

The SY2A23002A is available in a DFN2mmx2mm-8 package.

### Features

- 2.8V to 5.5V Input Voltage Range
- Up to 2A Output Current
- External Adjustable Voltage with  $\pm 1.5\%$  Reference Accuracy
- 1 $\mu$ A Shutdown Current (Typical)
- Fixed 2.35MHz Switching Frequency Minimizes Required External Components
- Selectable PWM and PFM Operating Modes
- 100% Duty-Cycle Capable
- Cycle-by-Cycle Current-Limit Protection
- Hiccup-Mode Short-Circuit Protection
- Thermal Shutdown
- Package: DFN2mmx2mm-8
- AEC-Q100 Qualified for Automotive Applications

### Applications

- Automotive Infotainment and Cluster
- Advanced Driver Assistance System (ADAS)
- Automotive Display

### Typical Application

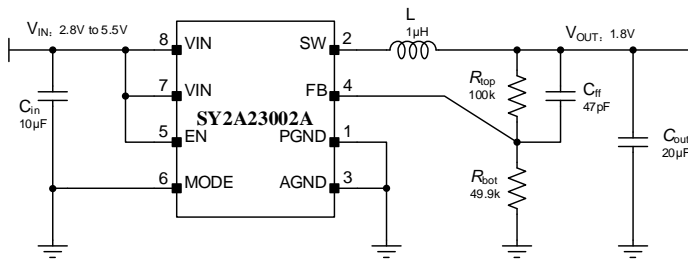


Figure 1. Schematic Diagram

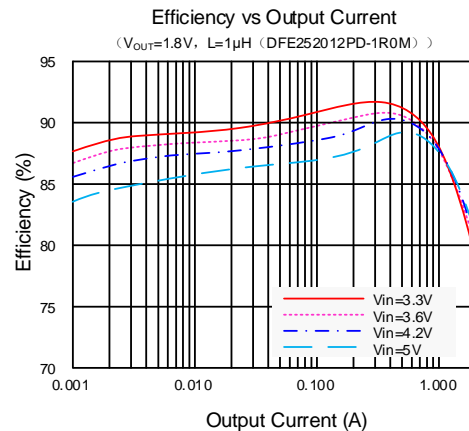


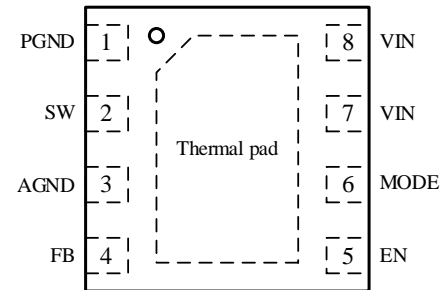
Figure 2. Efficiency vs Output Current

## Ordering Information

Ordering Part Number	Package Type	Top Mark
SY2A23002ADFD	DFN2x2-8 RoHS Compliant and Halogen Free	<b>FFW</b> xyz

*x = year code, y = week code, z = lot number code*

## Pinout (top view)



## Pin Description

Pin No	Pin Name	Pin Description
1	PGND	Power ground.
2	SW	Switching node.
3	AGND	Analog ground.
4	FB	Output voltage feedback pin. The output voltage reference is 0.6V.
5	EN	Device enable pin, logic-high enable. There is no pulldown resistor inside. Do not leave floating. The external resistor should be less than 500kΩ.
6	MODE	PFM/FCCM Mode selection. When the MODE pin is high, the device is forced to operate in FCCM. When the pin is low, the device enters PFM mode automatically during light load conditions. There is no pulldown resistor inside. Do not leave floating.
7, 8	V <sub>IN</sub>	V <sub>IN</sub> power supply.

## Block Diagram

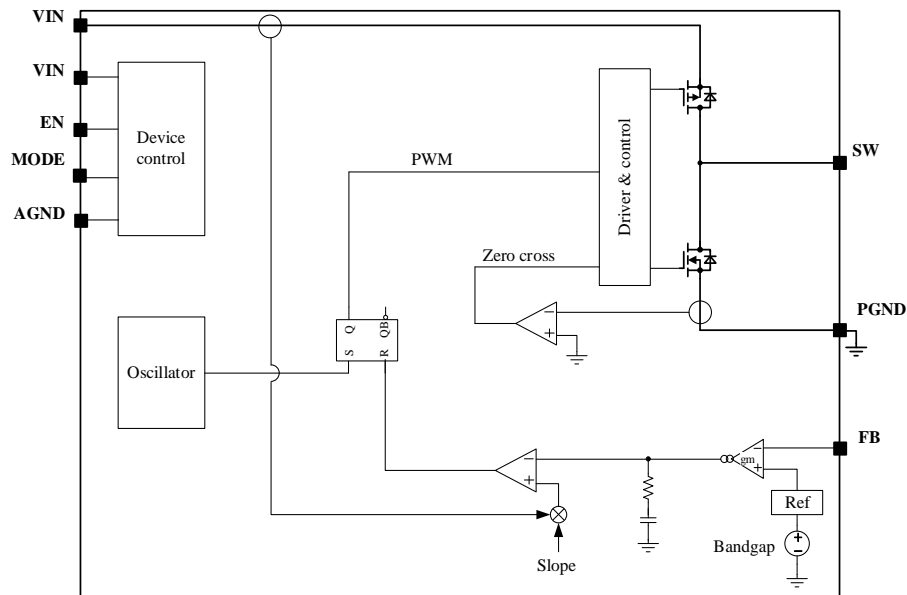


Figure 3. Functional Block Diagram

## Absolute Maximum Ratings

Parameter (Note 1)	Min	Max	Unit
$V_{IN}$	-0.3	6.5	V
FB, EN, MODE	-0.3	$V_{IN} + 0.3$	
Dynamic SW to GND Voltage in 20ns Duration	-3	$V_{IN} + 1.5$	
Junction Temperature, Operating	-40	150	°C
Lead Temperature (Soldering, 10 sec.)		260	
Storage Temperature	-65	150	
<b>ESD Susceptibility</b>			
HBM (Human Body Model)		2000	V
CDM (Charge Device Model) All Pins		500	

## Thermal Information

Parameter (Note 2)	Typ	Unit
$\theta_{JA}$ Junction-to-Ambient Thermal Resistance	56.5	°C/W
$\theta_{JC\_BOT}$ Junction-to-Case Thermal Resistance	14.5	
$\Psi_{JT}$	3.5	
$P_D$ Power Dissipation $T_A = 25^\circ\text{C}$	2.2	W

## Recommended Operating Conditions

Parameter (Note 3)	Min	Max	Unit
$V_{IN}$	2.8	5.5	V
Ambient Temperature	-40	125	°C

## Electrical Characteristics

( $2.8V \leq V_{IN} \leq 5.5V$ ,  $-40^{\circ}C \leq T_J \leq 125^{\circ}C$ . typical values at  $V_{IN} = 5V$  and  $T_J = 25^{\circ}C$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
$V_{IN}$	UVLO Rising Threshold	$V_{UVLO\_R}$	2.6	2.7	2.8	V	
	UVLO Falling Threshold	$V_{UVLO\_F}$	2.45	2.55	2.65	V	
	Shut Down Current A	$I_{SDA}$	$V_{EN} = 0V, T_J = 25^{\circ}C$	1	2	$\mu A$	
	Shut Down Current B	$I_{SDB}$	$V_{EN} = 0V, T_J = 125^{\circ}C$	6	12	$\mu A$	
	Quiescent Current	$I_Q$	$V_{MODE} = \text{logic low}, V_{EN} = \text{logic high}, \text{no load}$	22	35	$\mu A$	
EN	EN Logic 1 Threshold	$V_{EN\_H}$	1.2			V	
	EN Logic 0 Threshold	$V_{EN\_L}$			0.4	V	
Power Stage	Switching Frequency	$f_{sw}$	2	2.35	2.7	MHz	
	HS FET $R_{DS(ON)}$	$R_{DS(ON)\_HS}$	$V_{IN} = 5V$	120		m $\Omega$	
	LS FET $R_{DS(ON)}$	$R_{DS(ON)\_LS}$	$V_{IN} = 5V$	85		m $\Omega$	
	Discharge Resistor	$R_{DISCHARGE}$		200		$\Omega$	
Feedback and Soft-Start	Output Feedback Reference	$V_{REF}$	591	600	609	mV	
	Soft-Start Time	$T_{SS}$	$T_J = 25^{\circ}C$	0.1	0.2	0.5	ms
Mode	Input Bias Current	$I_{IN}$		0.01	1	$\mu A$	
	Logic 1 Threshold	$V_{MODE\_H}$	1.2			V	
	Logic 0 Threshold	$V_{MODE\_L}$			0.4	V	
Thermal Shutdown	Thermal Shutdown Threshold	$T_{SD}$	150	165	180	$^{\circ}C$	
	Thermal Shutdown Hysteresis	$T_{SDHYS}$	10	15	20	$^{\circ}C$	
Current Limit	Peak Current Limit	$I_{LIMIT\_P}$	2.8	3.5	4.2	A	
	Valley Foldback Current Limit	$I_{LIMIT\_V}$	2	2.8	3.5	A	
	Negative Valley Current Limit	$I_{LIMIT\_N}$	0.7	1.2	1.7	A	
Short-Circuit Protection	Short-Circuit Threshold	$V_{SCP}$	$V_{FB}$ as percent of $V_{REF}$	20	30	40	% $V_{REF}$
	Short-Circuit Response Time	$t_{SCP}$	From $V_{FB} < V_{SCP}$ to stop switching. No delay on the other side, $V_{IN} = 5V$ .	5	10	20	$\mu s$

**Note 1:** Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

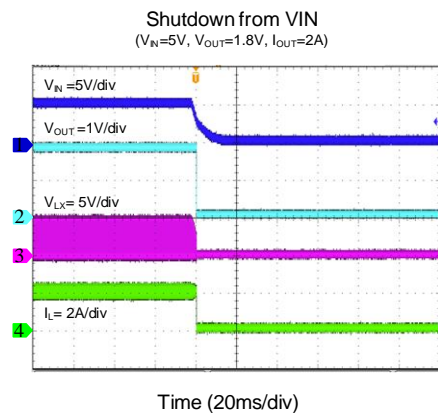
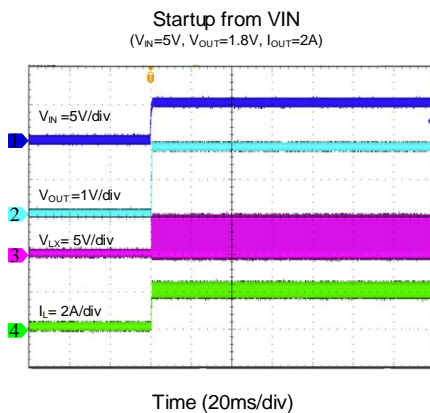
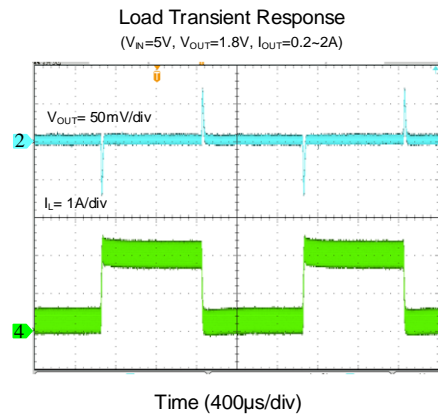
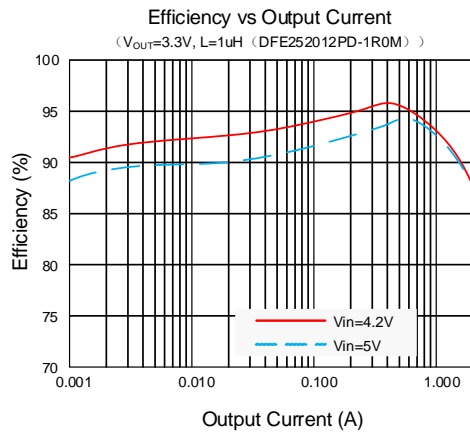
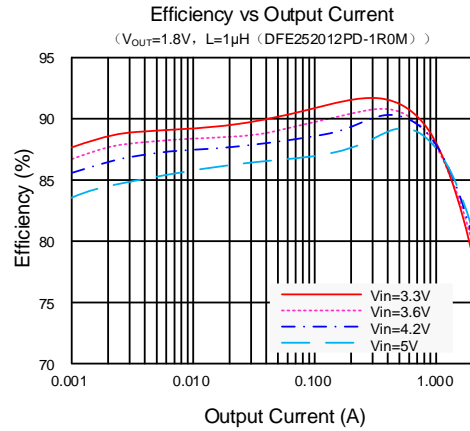
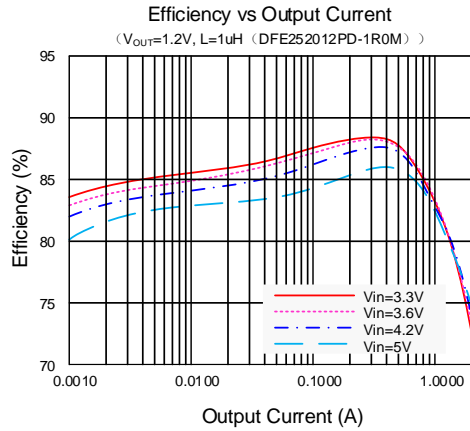
**Note 2:**  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25^{\circ}C$  on an 6cm × 6cm two-layer Silergy Evaluation Board with 1oz copper.

**Note 3:** The device is not guaranteed to electrical parameter outside its recommended operating conditions.

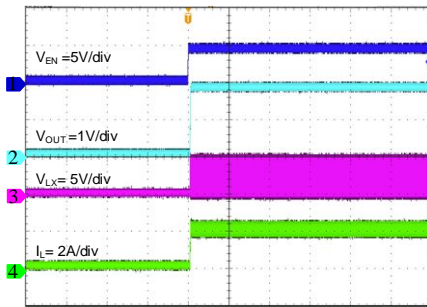
**Note 4:** Guaranteed by design. Not tested in production.

## Typical Performance Characteristics

( $T_A = 25^\circ\text{C}$ ,  $V_{IN} = 5\text{V}$ ,  $V_{OUT} = 1.8\text{V}$ ,  $L = 1\mu\text{H}$ ,  $C_{OUT} = 20\mu\text{F}$ , unless otherwise noted)

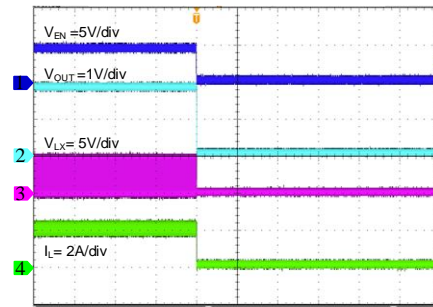


**Startup from VEN**  
( $V_{IN}=5V$ ,  $V_{OUT}=1.8V$ ,  $I_{OUT}=2A$ )



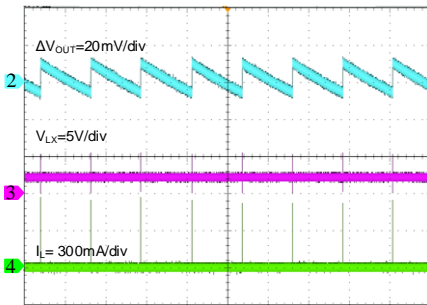
Time (10ms/div)

**Shutdown from VEN**  
( $V_{IN}=5V$ ,  $V_{OUT}=1.8V$ ,  $I_{OUT}=2A$ )



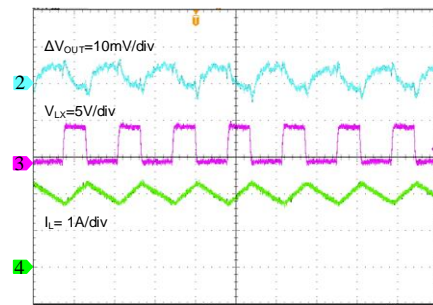
Time (10ms/div)

**Output Ripple**  
( $V_{IN}=5V$ ,  $V_{OUT}=1.8V$ ,  $I_{OUT}=0A$ )



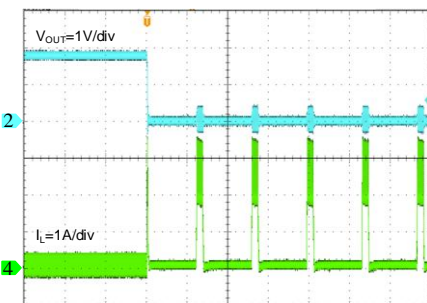
Time (40ms/div)

**Output Ripple**  
( $V_{IN}=5V$ ,  $V_{OUT}=1.8V$ ,  $I_{OUT}=2A$ )



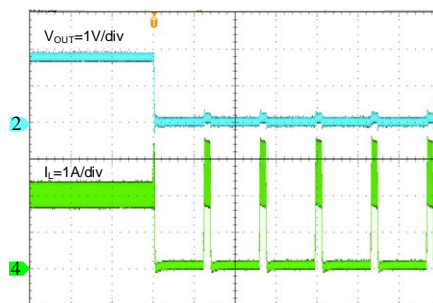
Time (400ns/div)

**Output Short Circuit**  
( $V_{IN}=5V$ ,  $V_{OUT}=1.8V$ ,  $I_{OUT}=0A$ )

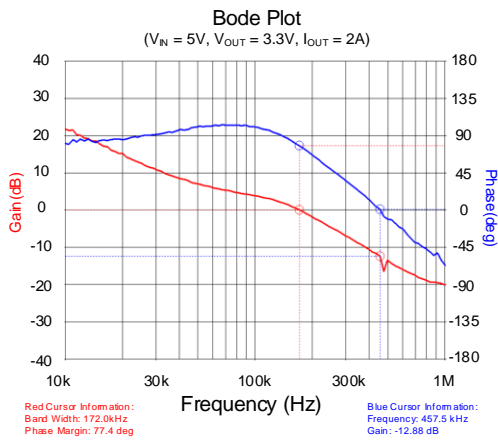
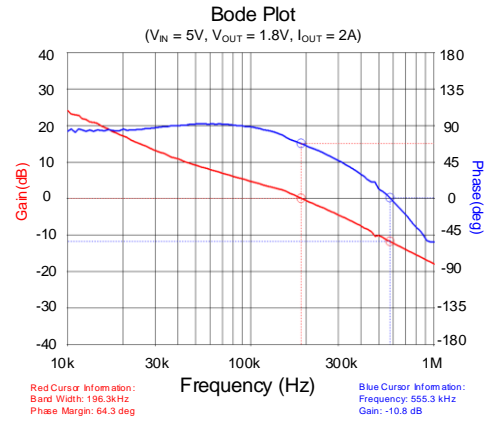
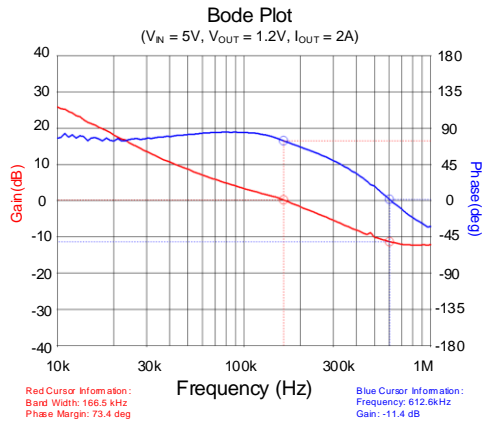


Time (2ms/div)

**Output Short Circuit**  
( $V_{IN}=5V$ ,  $V_{OUT}=1.8V$ ,  $I_{OUT}=2A$ )



Time (2ms/div)



## Applications Information

The SY2A23002A high-efficiency synchronous Buck converter can deliver 2A output current over an input voltage range from 2.8V to 5.5V. It uses built-in power MOSFETs to supply a resistor-configurable output voltage between 0.6V and  $V_{IN}$ . The fixed 2.35MHz switching frequency allows for small external inductor and capacitor values.

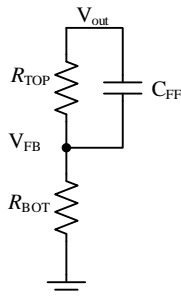
The selection process for the feedback resistors ( $R_{TOP}$  and  $R_{BOT}$ ), output inductor  $L$ , input capacitor  $C_{IN}$ , and output capacitor  $C_{OUT}$  is described in the following sections.

### Feedback Resistor-Divider $R_{TOP}$ and $R_{BOT}$

Choose  $R_{TOP}$  and  $R_{BOT}$  to program the proper output voltage. Choose large resistance values between 10k $\Omega$  and 105k $\Omega$  for both  $R_{TOP}$  and  $R_{BOT}$  to minimize power consumption under light loads (refer to the Typical Application section for recommended feedback Resistor values).

The output voltage can be configured using the following equation:

$$V_{OUT} = \left(1 + \frac{R_{TOP}}{R_{BOT}}\right) \times V_{FB}$$



where  $V_{FB}$  has a value of 0.6V (typ).

### Output Inductor $L$

Consider the following when choosing this inductor:

- 1) Choose the inductance to provide a ripple current that is approximately 40% of the maximum output current. The recommended inductance is calculated as:

$$L = \frac{V_{OUT}(1 - V_{OUT} / V_{IN,MAX})}{f_s \times I_{OUT,MAX} \times 0.4}$$

where  $f_s$  is the switching frequency and  $I_{OUT,MAX}$  is the maximum load current.

The SY2A23002A has high tolerance for ripple current amplitude variation. As a result, the final choice of inductance can vary slightly from the calculated value with no significant performance impact.

- 2) The inductor's saturation current rating must be greater than the peak inductor current under full load:

$$I_{SAT\_MIN} > I_{OUT\_MAX} + \frac{V_{OUT} \times (1 - V_{OUT} / V_{IN\_MAX})}{2f_s \times L}$$

- 3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency. Choose an inductor with smaller DCR to achieve a good overall efficiency.

### Input Capacitor $C_{IN}$

The ripple current through the input capacitor is calculated as:

$$I_{CIN\_RMS} = I_{OUT\_MAX} \times \sqrt{D \times (1 - D)}$$

The capacitance of the input capacitor is calculated as:

$$C_{IN} = \frac{I_{OUT} \times V_{OUT} \times (V_{IN} - V_{OUT})}{\Delta V_{IN} \times f_s \times \eta \times V_{IN}^2}$$

where  $\Delta V_{IN}$  is maximum allowed input voltage ripple.

For reliable operation, place a typical X7R or better grade ceramic capacitor close to the  $V_{IN}$  and GND pins. Care should be taken to minimize the loop area formed by  $C_{IN}$  and the  $V_{IN}/GND$  pins. A 10 $\mu$ F low-ESR ceramic capacitor is recommended for most applications. There is no need to place a 100nF ceramic capacitor in parallel between SY2A23002A and the 10 $\mu$ F capacitor.

### Output Capacitor $C_{OUT}$

Select the output capacitor  $C_{OUT}$  to handle the output ripple requirements. Both steady-state ripple and transient requirements must be taken into consideration when selecting  $C_{OUT}$ . It is recommended to use an X7R or better grade ceramic capacitor (refer to the Typical Application section for recommended capacitance values).



## Peak Current Mode Control

The Buck regulator provides a supply voltage lower than input voltage. The PWM controller measures the output voltage via a resistor divider connected between Pin FB and ground, and determines the appropriate pulse width duty cycle (on time).

The SY2A23002A incorporates a current mode control scheme, in which the PWM ramp signal is derived from the power switch current. This ramp signal is compared to the output of the error amplifier to control the on-time of the power switch. The oscillator is used as a fixed-frequency clock to ensure a constant operational frequency. The resulting control scheme features several advantages over conventional voltage mode control. First, derived directly from the inductor, the ramp signal responds immediately to line voltage changes. This eliminates the delay caused by the output filter and the error amplifier, which is commonly found in voltage mode controllers. The second benefit comes from inherent pulse-by-pulse current limiting by merely clamping the peak switching current. Finally, since current mode commands an output current rather than voltage, the filter offers only a single pole to the feedback loop. This allows for a simpler compensation.

## ON-OFF Sequence

When the device is enabled and the input voltage is above the UVLO threshold, the internal reference is activated and the analog circuits are settled. Afterwards, the soft-start is activated and the output voltage is ramped up.

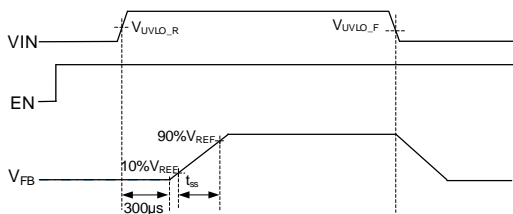


Figure 4. VIN ON/OFF Sequence

The device is enabled by setting the EN pin high. When the input voltage is above the UVLO threshold and the device is enabled, the output voltage ramps up from 10% to 90% of nominal value with  $t_{ss}$  of 200 $\mu$ s (typical).

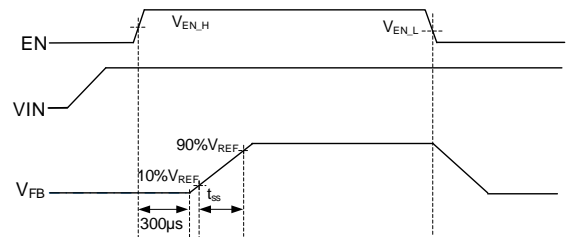


Figure 5. EN ON/OFF Sequence

## Adaptive Frequency Foldback at Minimum T<sub>OFF</sub> Operation (Dropout)

The SY2A23002A provides adaptive frequency reduction during large-duty-cycle operation when minimum T<sub>OFF</sub> is reached. Unlike conventional peak-current control, this approach ensures the stability of the circuit during dropout operation. When V<sub>IN</sub> drops below the configured V<sub>OUT</sub> voltage, the SY2A23002A will enter dropout mode, wherein its high-side FET will always be ON. Normal operation resumes when V<sub>IN</sub> exceeds the target V<sub>OUT</sub> level.

## Light-Load Operation

The SY2A23002A supports automatic PWM/PFM operation when the external MODE pin is set low. The converter operates in fixed-frequency PWM mode at medium to heavy loads, and in PFM mode during light loads, maintaining high efficiency over the entire load-current range.

## Protection Features

The SY2A23002A provides integrated output short-circuit protection, output overcurrent protection, and thermal shutdown protection.

Table 1. Protection Features

Protection	Threshold	Deglint Time	Operation
Thermal Shutdown	Rising: 165°C Falling: 150°C	–	Shutdown when temperature >165°C. Restart when temperature <150°C.
Cycle-by-Cycle Current Limit	3.5A	–	Peak limit = valley limit. Valley foldback to 80% after 3 cycles.
Output SCP	V <sub>FB</sub> < 30% V <sub>REF</sub>	10 $\mu$ s	Hiccup time = 2.5ms.

## Current Limit

The SY2A23002A features cycle-by-cycle current-limit protections. When the current-sense amplifier detects a voltage that exceeds the peak current limit, the HS FET is turned off for the remainder of the cycle. See Figure 6.

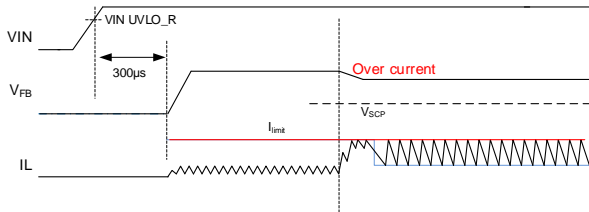


Figure 6. Cycle-by-Cycle Current Limit

## Short-Circuit Protection

The SY2A23002A will attempt to protect the power MOSFET from damage in the event of a short circuit at the output. After the initial short-circuit blanking time  $T_{SCP}$ , when the output voltage falls below the short-circuit threshold, the device will be turned off for the hiccup time and then go through the soft-start time  $T_{SS}$ . See Figure 7.

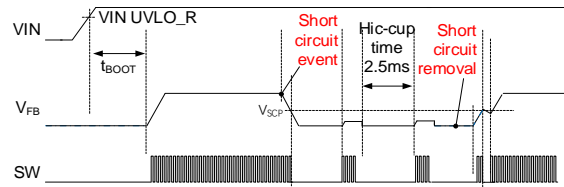


Figure 7. Short-Circuit Protection

## Overtemperature Protection

The SY2A23002A enters thermal shutdown when the junction temperature exceeds 165°C (typical). In this mode, the high-side switch and low-side switch are turned off. When the junction temperature falls below 150°C (typical), the Buck will automatically be re-enabled. See Figure 8.

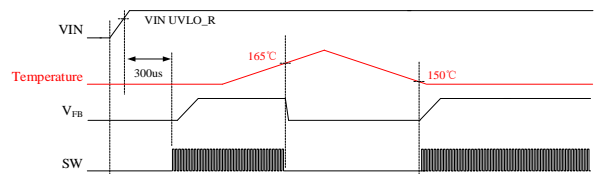
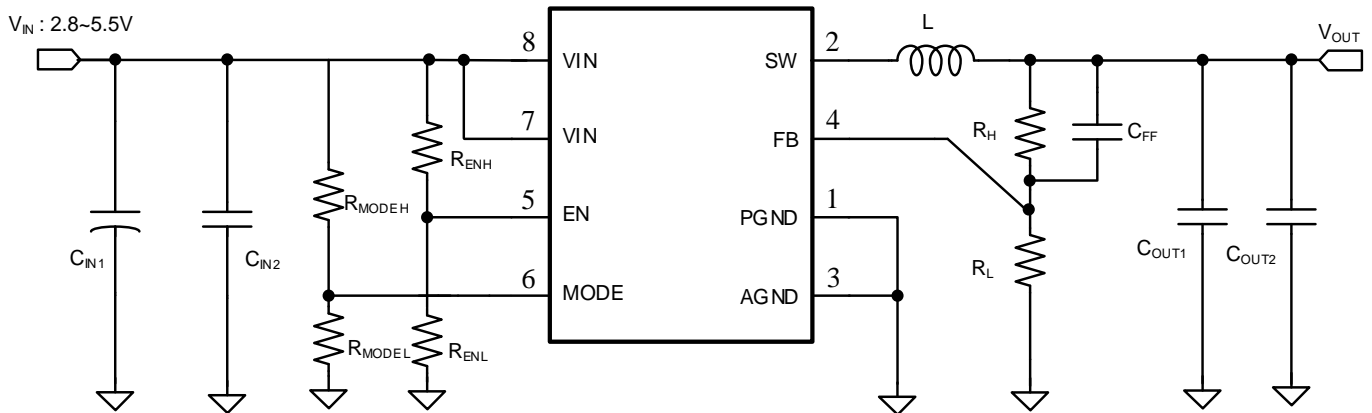


Figure 8. Overtemperature Protection

## Application Schematic ( $V_{OUT} = 1.8V$ )



## BOM List

Reference Designator	Description	Part Number	Manufacturer
C <sub>IN1</sub>	47μF/50V Electrolytic Capacitor		
C <sub>IN2</sub> , C <sub>OUT1</sub> , C <sub>OUT2</sub>	10μF/6.3V/X7T, 0603	GCM188D70J106ME36D	muRata
L	1μH/inductor,3.2A	DFE252012PD-1R0M	muRata
C <sub>FF</sub>	47pF/50V/C0G, 0603		
R <sub>H</sub>	100kΩ, 1%, 0603		
R <sub>L</sub>	49.9kΩ, 1%, 0603		
R <sub>MODEH</sub>	10kΩ, 1%, 0603		
R <sub>MODEL</sub>	1MΩ, 1%, 0603		
R <sub>ENH</sub>	10kΩ, 1%, 0603		
R <sub>ENL</sub>	1MΩ, 1%, 0603		

## Recommended Component Values for Typical Applications

Table 2. Setting the Output Voltage ( $C_{OUT} \geq 20\mu F$ ,  $V_{OUT} \geq 0.6V$ )

V <sub>OUT</sub> (V)	R <sub>H</sub> (kΩ)	R <sub>L</sub> (kΩ)	C <sub>FF</sub> (pF)	L/Part Number	C <sub>OUT</sub>
0.6	0	NC	NC	1.0μH/DFE252012PD-1R0M	10μF*3/6.3V, 0603, X7T
0.8	10	30	47	1.0μH/DFE252012PD-1R0M	10μF*2/6.3V, 0603, X7T
0.9	15	30	47	1.0μH/DFE252012PD-1R0M	10μF*2/6.3V, 0603, X7T
1.0	20	30	47	1.0μH/DFE252012PD-1R0M	10μF*2/6.3V, 0603, X7T
1.1	20	24	68	1.0μH/DFE252012PD-1R0M	10μF*2/6.3V, 0603, X7T
1.2	51	51	47	1.0μH/DFE252012PD-1R0M	10μF*2/6.3V, 0603, X7T
1.5	30	20	47	1.0μH/DFE252012PD-1R0M	10μF*2/6.3V, 0603, X7T
1.8	100	49.9	47	1.0μH/DFE252012PD-1R0M	10μF*2/6.3V, 0603, X7T
2.5	105	33	47	1.0μH/DFE252012PD-1R0M	10μF*2/6.3V, 0603, X7T
3.3	100	22.1	47	1.0μH/DFE252012PD-1R0M	10μF*2/6.3V, 0603, X7T

**Table 3. Setting the Output Voltage ( $C_{OUT} = 10\mu F$ ,  $V_{OUT} \geq 1.2V$ )**

$V_{OUT}(V)$	$R_H(k\Omega)$	$R_L(k\Omega)$	$C_{FF}(pF)$	L/Part Number	$C_{OUT}$
1.2	10	10	22	1.0 $\mu$ H/DFE252012PD-1R0M	10 $\mu$ F/6.3V, 0603, X7T
1.5	30	20	22	1.0 $\mu$ H/DFE252012PD-1R0M	10 $\mu$ F/6.3V, 0603, X7T
1.8	30	15	22	1.0 $\mu$ H/DFE252012PD-1R0M	10 $\mu$ F/6.3V, 0603, X7T
2.5	47.5	15	22	1.0 $\mu$ H/DFE252012PD-1R0M	10 $\mu$ F/6.3V, 0603, X7T
3.3	100	22.1	10	1.0 $\mu$ H/DFE252012PD-1R0M	10 $\mu$ F/6.3V, 0603, X7T

## Layout Design

Follow these PCB layout guidelines for optimal performance and thermal dissipation:

- Maximize the PCB copper area connected to the GND pin to achieve the best thermal and noise performance. Using a separate layer as a ground plane is highly recommended.

- To avoid EMI, minimize the PCB copper area associated with the SW pin.
- To avoid potential noise, ensure that the feedback components  $R_H$  and  $R_L$ , and the trace connecting to the FB pin, are **not** adjacent to the SW net on the PCB layout.

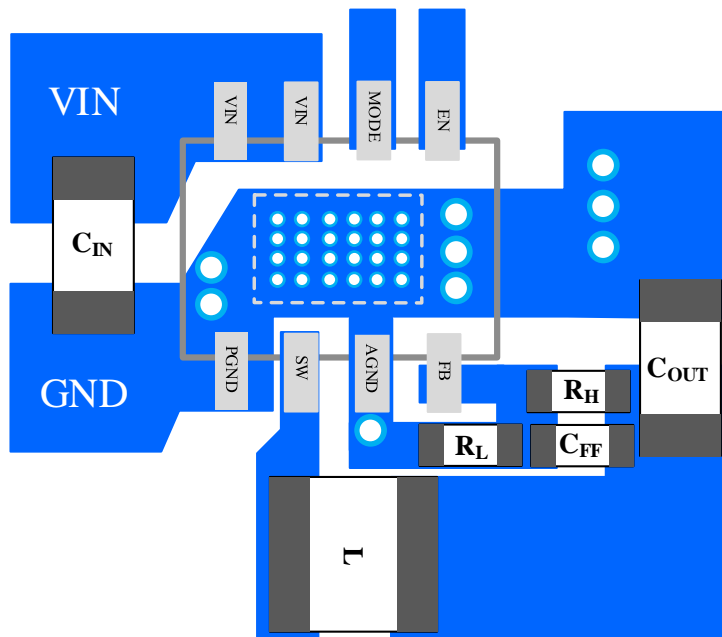
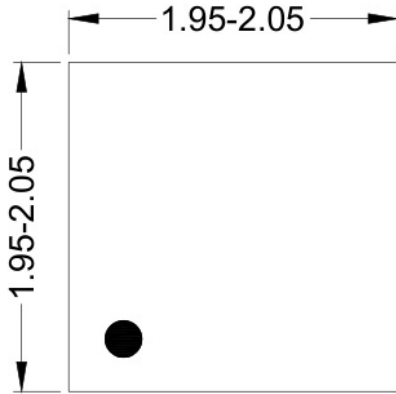
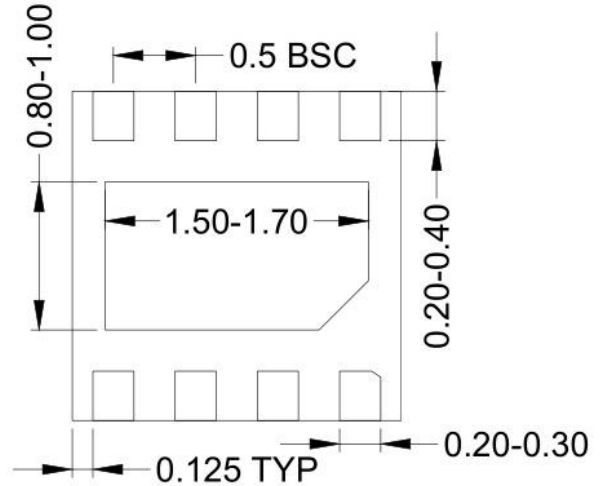


Figure 9. PCB Layout Suggestion

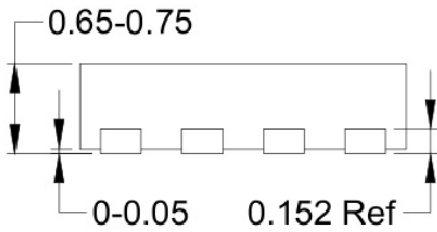
DFN2x2-8 Package Outline Drawing



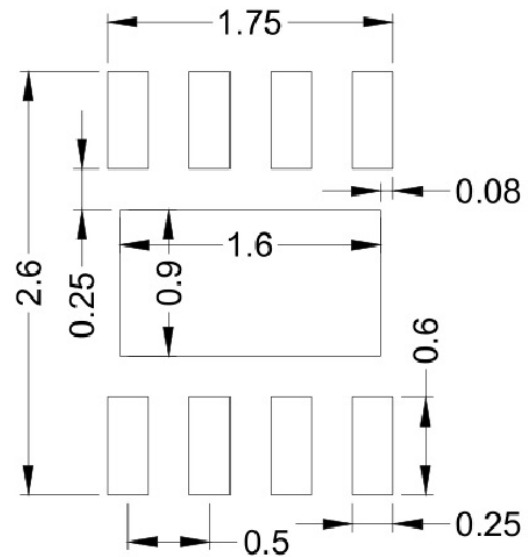
Top View



Bottom View



Side View

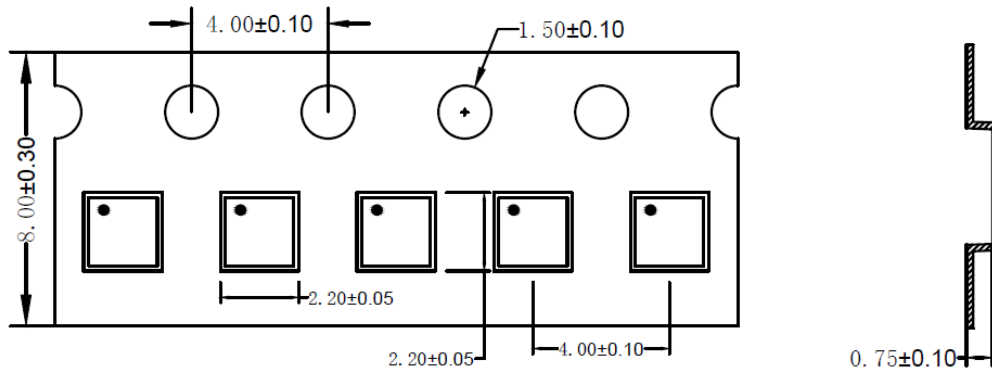


Recommended PCB layout  
(Reference only)

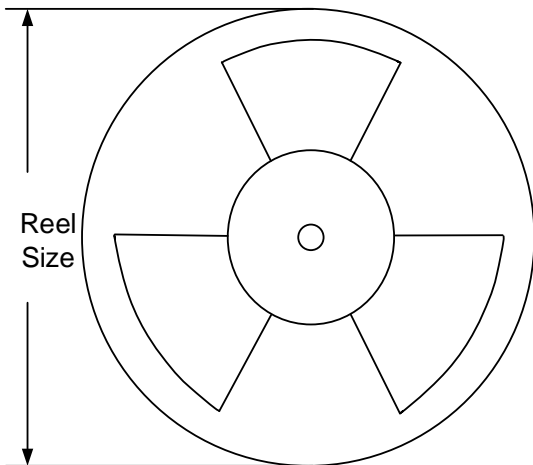
**Note:** All dimensions are in millimeters and exclude mold flash and metal burr.

## Taping and Reel Specification

### DFN2x2 Taping Orientation



### Carrier Tape and Reel Specification for Packages



Package types	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
DFN2x2	8	4	7"	400	400	3000

**Others: NA**

## Revision History

The revision history provided is for informational purpose only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

Date	Revision	Change
Jul.11, 2023	Revision 0.9	Initial Release
Oct. 09, 2023	Revision 0.9A	<ol style="list-style-type: none"> <li>1. Add the application circuit diagram and recommended parameters.</li> <li>2. Add Bode Plots.</li> <li>3. Modify the descriptions of Absolute Maximum Ratings and Recommended</li> <li>4. Modify the recommended input voltage range and ISD current description.</li> <li>5. Modify the recommended voltage divider range.</li> <li>6. Modify the short circuit waveform description.</li> <li>7. Add description of ON-OFF sequence.</li> <li>8. Add description of peak current mode.</li> <li>9. Modify operation mode from PSM to PFM of Key Features in page 1.</li> <li>10. Modify the description of thermal resistance test condition.</li> <li>11. Modify the description of Current limit and Short Circuit Protection.</li> </ol>

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